



Material Content Data Sheet



Sales Product Name		TLE4963-2M		Issued		25. September 2017			
MA#		MA001318110							
Package		PG-SOT23-3-15		Weight*		9.78 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.220	2.25	2.25	22458	22458	
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		74		
		non noble metal	titanium	7440-32-6	0.004	0.04		369	
		non noble metal	chromium	7440-47-3	0.011	0.11		1106	
wire	noble metal	non noble metal	copper	7440-50-8	3.590	36.71	36.87	367146	368695
		noble metal	gold	7440-57-5	0.023	0.24	0.24	2360	2360
		organic material	carbon black	1333-86-4	0.055	0.56		5618	
encapsulation	plastics	epoxy resin	-	1.181	12.08		120790		
		inorganic material	silicondioxide	60676-86-0	4.257	43.54	56.18	435405	561813
leadfinish	non noble metal	tin	7440-31-5	0.152	1.55	1.55	15496	15496	
plating	noble metal	silver	7440-22-4	0.149	1.52	1.52	15197	15197	
glue	plastics	epoxy resin	-	0.024	0.24		2447		
		noble metal	silver	7440-22-4	0.113	1.15	1.39	11534	13981
*deviation	< 10%				Sum in total:		100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com